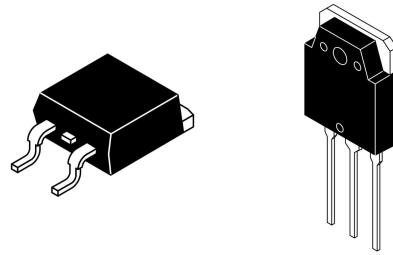


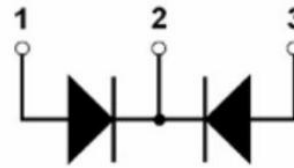
Features

- Ultrafast Recovery Time
- Soft Recovery Characteristics
- Low Recovery Loss
- Low Forward Voltage
- High Surge Current Capability
- Low Leakage Current



Applications

- Freewheeling, Snubber, Clamp
- Inversion Welder
- Plating Power Supply
- Ultrasonic Cleaner and Welder
- UPS
- PFC

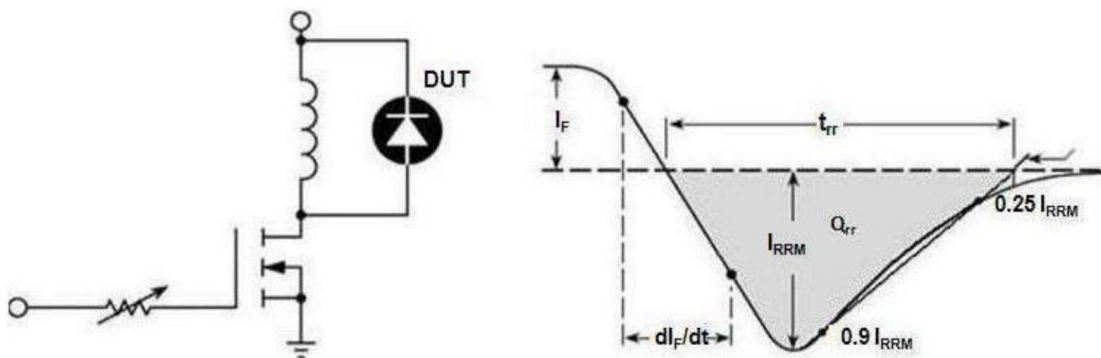


Absolute Maximum Ratings

Parameter	Symbol	Test Conditions	Values	Unit
Maximum D.C. Reverse Voltage	V_R		300	V
Maximum Repetitive Reverse Voltage	V_{RRM}		300	
Average Forward Current	$I_{F(AV)}$	$T_C=100^{\circ}\text{C}$, Per Diode	30	A
		$T_C=100^{\circ}\text{C}$, Per Package	60	
RMS Forward Current	$I_{F(RMS)}$	$T_C=100^{\circ}\text{C}$, Per Diode	42	
Non-Repetitive Surge Forward Current	I_{FSM}	$T_C=45^{\circ}\text{C}$, $t=10\text{ms}$, 50Hz, Sine	480	
Power Dissipation	P_D		156	W
Junction Temperature	T_J		-55~150	$^{\circ}\text{C}$
Storage Temperature Range	T_{STG}		-55~150	
Thermal Resistance Junction-to-Case	$R_{\theta JC}$	F60D33E	0.8	$^{\circ}\text{C/W}$
		F60D33B	0.46	

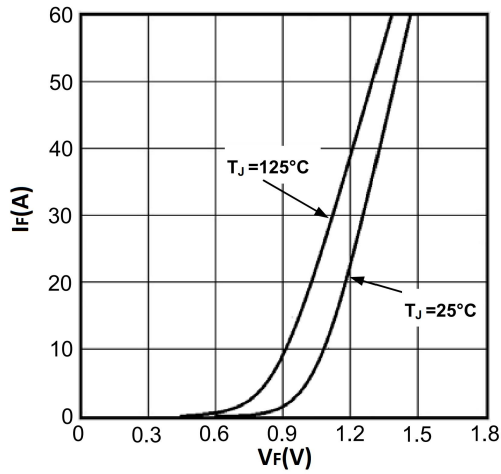
Electrical Characteristics($T_C=25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Reverse Leakage Current	I_{RM}	$V=300\text{V}$	-	-	10	μA
		$V=300\text{V}, T=125^\circ\text{C}$	-	-	10000	
Forward Voltage	V_F	$I=30\text{A}$	-	1.25	1.8	V
		$I=30\text{A}, T=125^\circ\text{C}$	-	1.12	-	
Reverse Recovery Time	t_{rr}	$I_F=1\text{A}, V=30\text{V}, di/dt=-200\text{A}/\mu\text{s}$	-	22	-	ns
Reverse Recovery Time	t_{rr}	$V=150\text{V}, I=30\text{A}$ $di/dt=-200\text{A}/\mu\text{s}, T=25^\circ\text{C}$	-	35	-	
Max. Reverse Recovery Current	I_{RRM}		-	2.5	-	A
Reverse Recovery Time	t_{rr}	$V=150\text{V}, I=30\text{A}$ $di/dt=-200\text{A}/\mu\text{s}, T=125^\circ\text{C}$	-	70	-	ns
Max. Reverse Recovery Current	I_{RRM}		-	6.8	-	A

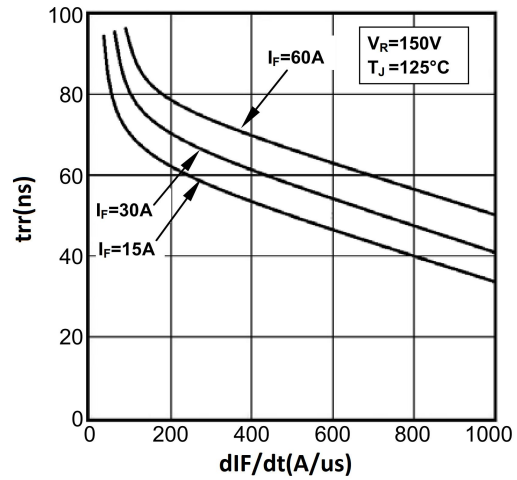
Diode Reverse Recovery Test Circuit and Waveform

Electrical characteristics(Curves)

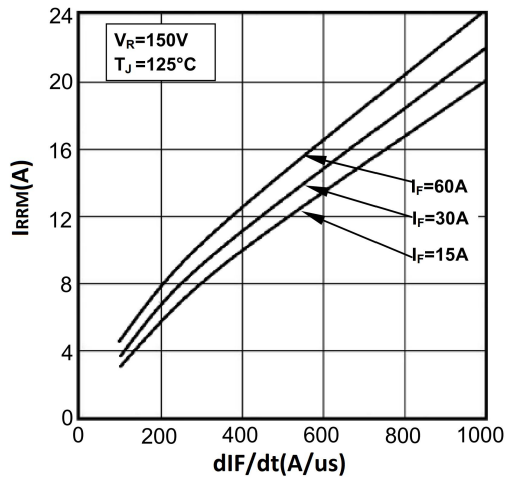
Forward Voltage Drop vs Forward Current



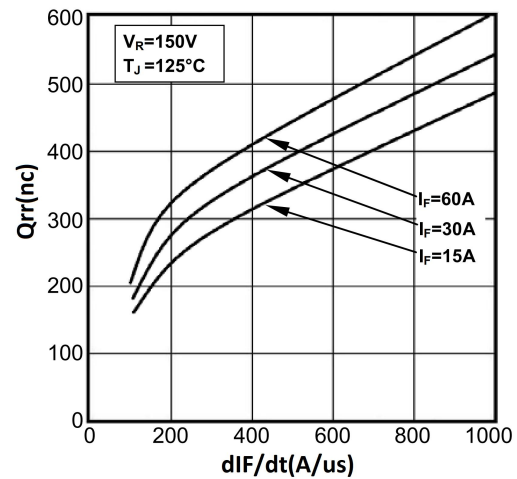
Reverse Recovery Time vs dI_F/dt



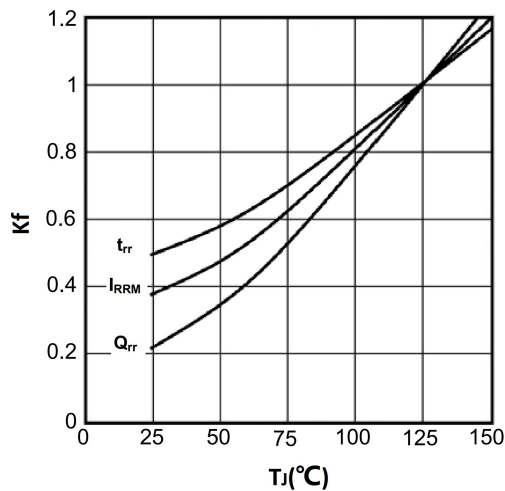
Reverse Recovery Current vs dI_F/dt



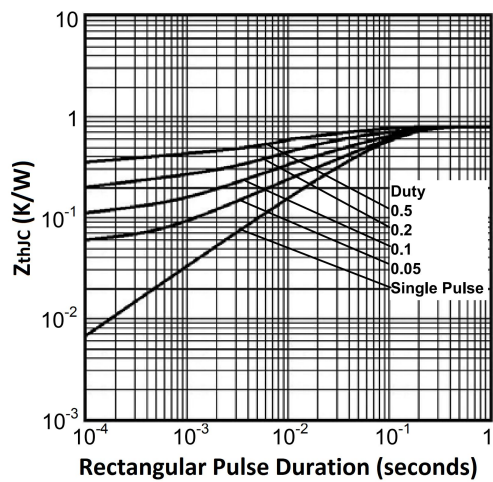
Reverse Recovery Charge vs dI_F/dt



Dynamic Parameters vs Junction Temperature



Transient Thermal Impedance



Package outline dimension

